

Publication list format

- 1 **List format** : English/Times New Roman, Chinese/標楷體, 10 pt, single space, if published in Chinese, please translate into English and place (in Chinese) after the English title.
- 2 **Author's English and Chinese name** : Single space, center aligned.
- 3 **Within list Column, separate each item by comma (,) and end with a period (.):**
 - 3.1 **Author name** : Abbreviation, e.g. Bing-Ming Cheng should be abbreviated as B.-M. Cheng, left-justified.
 - 3.2 **Publication\Patent title** : Open quotation mark (“) / not italic, *Publication\Patent title* : Italic with first letter of each word capitalized, if title is in Chinese, please list Chinese title in [] symbol and place after English title, close quotation mark (”) / not italic.
 - 3.3 **Journal name\Volume number\Patent number and issuing office\School name** : Journal name in capital letters; volume number in bold and leave a space between journal name and volume number.
 - 3.4 **Starting page (Western Year)** : Please leave a space between starting page and western year and list western year in brackets ().
 - 3.5 **Beamline number percentage** : If the publication is the result of experiments performed on several beamlines, please list the contributing percentage of each beamline.

Note: Proceeding should be grouped as Conference papers, Conference papers must include Proceeding and page number to illustrate that the Proceeding has publications. Further, please list city, country, and date of conference after starting page number.

Publication list format

Principal Investigator's English Name
(Principal Investigator's Chinese Name)

Publication Based on Experiments Performed at NSRRC Beamlines

1. C.-H. Hsu, H.-Y. Lee, Y.-W. Hsieh, Y. P. Stetsko, M.-T. Tang, K. S. Liang, N. T. Yeh, J.-I. Chyi, and D. Y. Noh, “*X-ray Scattering Studies on InGaAs Quantum Dots*”, *PHYSICA B* **336**, 98 (2003). (17B1-50%, 15B1-25%, 17C1-25%)

Patents

1. H. Yang, M.-C. Chou, C.-T. Pan, and C.-K. Mu, “*Method of Making Molds for Manufacturing Multiple-lead Microstructures [以能量光束製造高精度微細零件之製造方法及模具裝置追加一]*”, R.O.C. Patent 88291 (2002).